

SOT1178-1

DFN2110-9: plastic extremely thin small outline package; no leads; 9 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2110-9
Package type industry code	DFN2110-9
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	3-6-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2	-	2.1	2.2	mm
E	package width	0.9	-	1	1.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	9	-	



2. Package outline

DFN2110-9: plastic extremely thin small outline package; no leads
9 terminals; body 1 x 2.1 x 0.5 mm

SOT1178-1

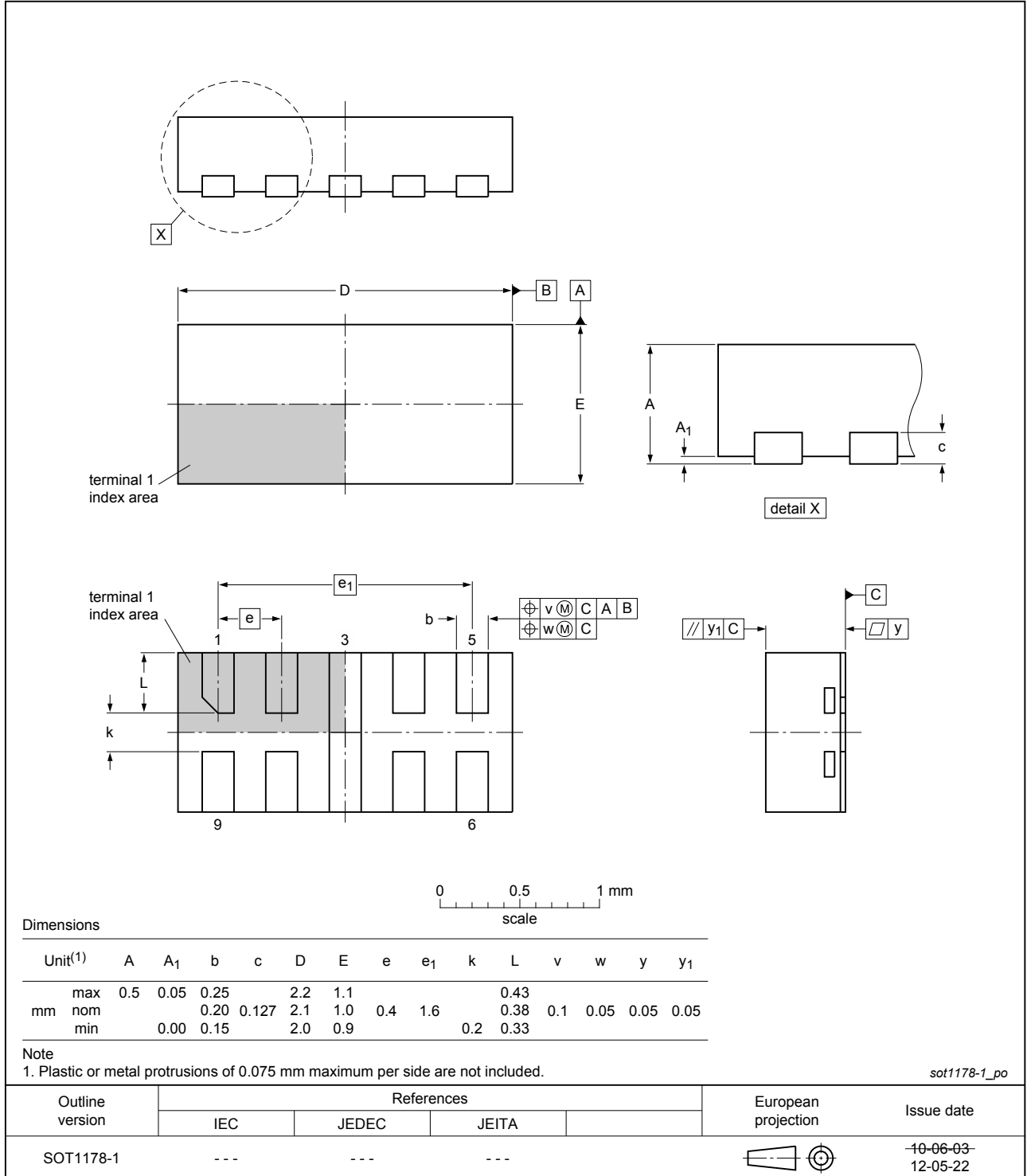


Fig. 1. Package outline DFN2110-9 (SOT1178-1)

3. Soldering

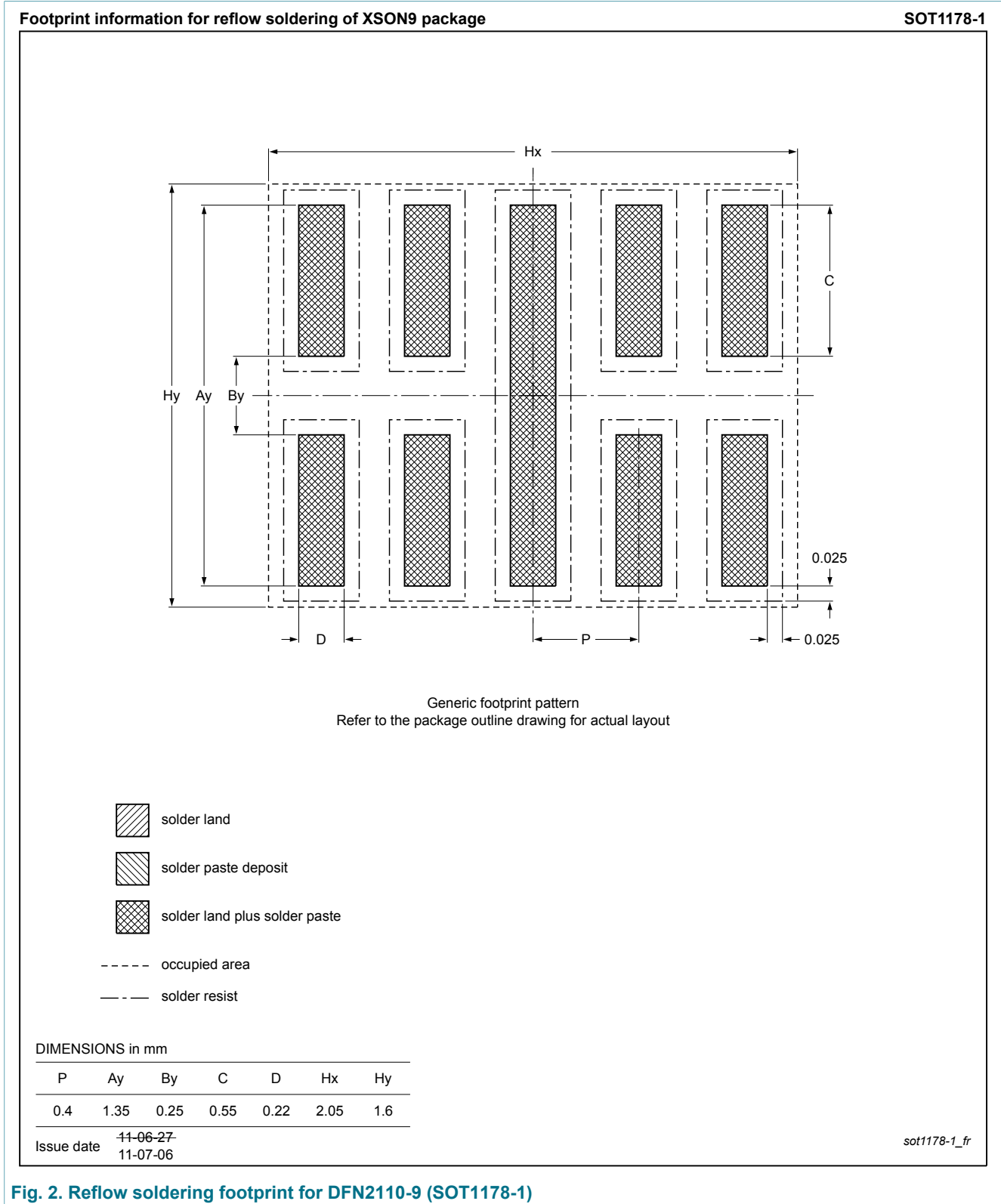


Fig. 2. Reflow soldering footprint for DFN2110-9 (SOT1178-1)

4. Legal information

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